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IEC TR 63091:2017

IEC Title

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Preferred number series for resistors and capacitors
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Environmental testing - Part 2-69: Tests - Test Te/Tc: Solderability testing of electronic components and printed bo
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Electronics assembly technology - Electronic modules
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TC	Technical Committee Name	IS No#
TC 40	Capacitors and resistors for electronic equipment	IS 8186 : 2020
TC 40	Capacitors and resistors for electronic equipment	IS 824 : 2021
TC 91	Electronics assembly technology	IS/IEC 60068-2-20) : 2021
TC 91	Electronics assembly technology	IS/IEC 60068-2-69) : 2017
TC 91	Electronics assembly technology	IS/IEC 60068-2-82) : 2019
TC 91	Electronics assembly technology	IS/IEC 60068-2-83) : 2011
TC 40	Capacitors and resistors for electronic equipment	IS/IEC 60115-1 : 2020
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400100 : 1988
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400101 : 1988
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400200 : 1992
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400400 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400401 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400500 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400501 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400600 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 400601 : 1993
SC 47D	Semiconductor devices packaging	IS 5001 : 2018
TC 40	Capacitors and resistors for electronic equipment	IS/IEC 60195 : 2016
TC 40	Capacitors and resistors for electronic equipment	IS 13554 : 2020
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300000 : 1988
TC 40	Capacitors and resistors for electronic equipment	IS 7305 : 2018
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300100 : 1988
TC 40	Capacitors and resistors for electronic equipment	IS/QC 301800 : 2001
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TC 40	Capacitors and resistors for electronic equipment	IS/QC 302400 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/IEC 60384-141-1) : 2016
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TC 40	Capacitors and resistors for electronic equipment	IS/QC 300201 : 2000
TC 40	Capacitors and resistors for electronic equipment	IS/QC 301301 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS 9256 (Part 1) : 2019
TC 40	Capacitors and resistors for electronic equipment	IS/QC 301200 : 1993
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TC 40	Capacitors and resistors for electronic equipment	IS/QC 300701 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300800 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300801 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/IEC 60384-4 : 2016
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300301 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300600 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/QC 300601 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS/IEC 60384-9 : 2015
TC 40	Capacitors and resistors for electronic equipment	IS 8872 (Part 1) : 2018
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TC 40	Capacitors and resistors for electronic equipment	IS/QC 440000 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS 11534 (Part 1) : 1985

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TC 47	Semiconductor devices	IS 14901 (Part 1) : 2010
SC 47E	Discrete semiconductor devices	IS 14901 (Part 2) : 2020
SC 47E	Discrete semiconductor devices	IS 14901 (Part 3) : 2016
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SC 47E	Discrete semiconductor devices	IS 14901 (Part 8) : 2020
SC 47A	Integrated circuits	IS 12970 (Part 1) : 2010
SC 47A	Integrated circuits	IS 12970 (Part 2) : 2021
SC 47A	Integrated circuits	IS/QC 760000 : 1994
SC 47A	Integrated circuits	IS/QC 760100 : 1995
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SC 47A	Integrated circuits	IS 12970 (Part 3) : 2021
SC 47A	Integrated circuits	IS/QC 790202 : 1993
TC 40	Capacitors and resistors for electronic equipment	IS 15866 (Part 1) : 2010
TC 40	Capacitors and resistors for electronic equipment	IS 13247 (Part 1) : 2021
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TC 40	Capacitors and resistors for electronic equipment	IS/QC 420000 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 420100 : 1994
TC 40	Capacitors and resistors for electronic equipment	IS/QC 420102 : 1993
TC 91	Electronics assembly technology	IS/IEC 61189-1 : 2001
TC 91	Electronics assembly technology	IS/IEC 61189-2 : 2006
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TC 91	Electronics assembly technology	IS/IEC 62137-4 : 2014
TC 91	Electronics assembly technology	IS/IEC 62326-1 : 2002
TC 91	Electronics assembly technology	IS/IEC 62326-20 : 2016
TC 91	Electronics assembly technology	IS/IEC 62421 : 2007
TC 40	Capacitors and resistors for electronic equipment	IS/IEC/TR 63091 : 2017

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; heat of devices with leads
ards by the wetting balance (force measurement) method
onic assemblies
ng devices (SMD) by the wetting balance method using solder paste
d methodology
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ce mount devices

; for through-hole assembly on circuit boards (THT)
leads for through-hole assembly on circuit boards (THT), for general electronic equipment, classification level G
sembly on circuit boards (THT) or for assembly on chassis
/orks with individually measurable resistors
idually measurable resistors, all of equal value and equal dissipation. Assessment level E
all resistors are individually measurable
not all resistors are individually measurable. Assessment level E

/ power film resistors for general electronic equipment, classification level G

ephthalate film dielectric DC capacitors
e-terephthalate film dielectric d.c. capacitors - Assessment levels E and EZ
or surface mounting with solid electrolyte and porous anode, style I. Assessment level E
acitors with solid (MnO₂) and non-solid electrolyte
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ctric, Class 1
ielectric, Class 1 - Assessment level EZ
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ene-terephthalate film dielectric metal foil DC capacitors
ric metal foil d.c. capacitors
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netic interference suppression and connection to the supply mains
magnetic interference suppression and connection to the supply mains - Assessment level DZ
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s for which safety tests are appropriate - Test methods and general requirements

rs. Assessment level E

gs of discrete devices

lar monolithic digital integrated circuit gates (excluding uncommitted logic arrays)
ition for HCMOS digital integrated circuits (series 54/74 HC, 54/74 HCT, 54/74 HCU)
r complementary MOS digital integrated circuits, series 4000 B and 4000 UB

ation for monolithic integrated operational amplifiers
ts and hybrid film integrated circuits
film integrated circuits on the basis of qualification approval procedures
brid film integrated circuits on the basis of qualification approva lprocedures
film integrated circuits on the basis of the capability approval procedures
brid film integrated circuits on the basis of the capability approval procedures